

HD74LVCZ244A

Octal Buffers / Line Drivers with 3-state Outputs

REJ03D0371-0300
(Previous ADE-205-230A (Z))
Rev.3.00
Aug. 18, 2004

Description

The HD74LVCZ244A has eight line drivers with three state outputs in a 20 pin package. This device is a noninverting buffer and has two active low enables ($\overline{1G}$ and $\overline{2G}$). Each enable independently controls four buffers.

When V_{CC} is between 0 and 1.5 V, the device is in the high impedance state during power up or power down.

Low voltage and high-speed operation is suitable at battery drive product (note type personal computer) and low power consumption extends the life of a battery for long time operation.

Features

- $V_{CC} = 2.7$ to 5.5 V
- All inputs V_{IH} (Max) = 5.5 V (@ $V_{CC} = 0$ to 5.5 V)
- All outputs V_O (Max) = 5.5 V (@ $V_{CC} = 0$ V or output off state)
- Typical V_{OL} ground bounce < 0.8 V (@ $V_{CC} = 3.3$ V, $T_a = 25^\circ\text{C}$)
- Typical V_{OH} undershoot > 2.0 V (@ $V_{CC} = 3.3$ V, $T_a = 25^\circ\text{C}$)
- High impedance state during power up and power down
- Power off disables outputs, permitting live insertion
- High output current ± 24 mA (@ $V_{CC} = 3.0$ to 5.5 V)
- Ordering Information

Part Name	Package Type	Package Code	Package Abbreviation	Taping Abbreviation (Quantity)
HD74LVCZ244AFPEL	SOP-20 pin (JEITA)	FP-20DAV	FP	EL (2,000 pcs/reel)
HD74LVCZ244ATELL	TSSOP-20 pin	TTP-20DAV	T	ELL (2,000 pcs/reel)

Function Table

Inputs

$\overline{G}$	A	Output Y
H	X	Z
L	H	H
L	L	L

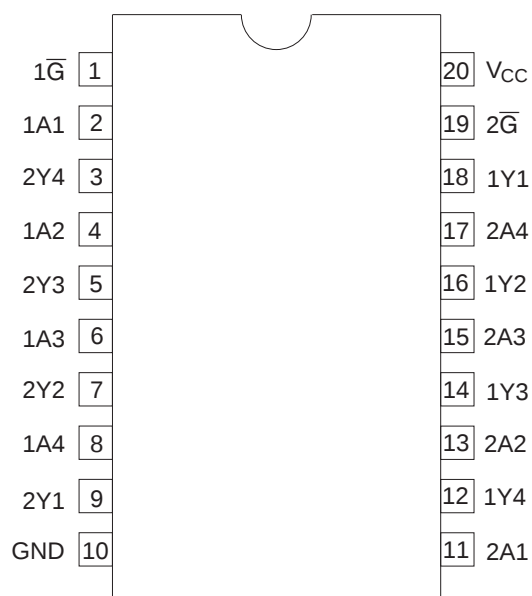
H: High level

L: Low level

X: Immaterial

Z: High impedance

Pin Arrangement



(Top view)

Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	-0.5 to 7.0	V	
Input voltage	V_I	-0.5 to 7.0	V	
Output voltage	V_O	-0.5 to 7.0	V	Output "Z" or V_{CC} : OFF
		-0.5 to $V_{CC}+0.5$		Output "H" or "L"
Input diode current	I_{IK}	-50	mA	$V_I < 0$
Output diode current	I_{OK}	-50	mA	$V_O < 0$
Output current	I_O	± 50	mA	
V_{CC} , GND current	I_{CC} or I_{GND}	± 100	mA	
Storage temperature	Tstg	-65 to 150	°C	

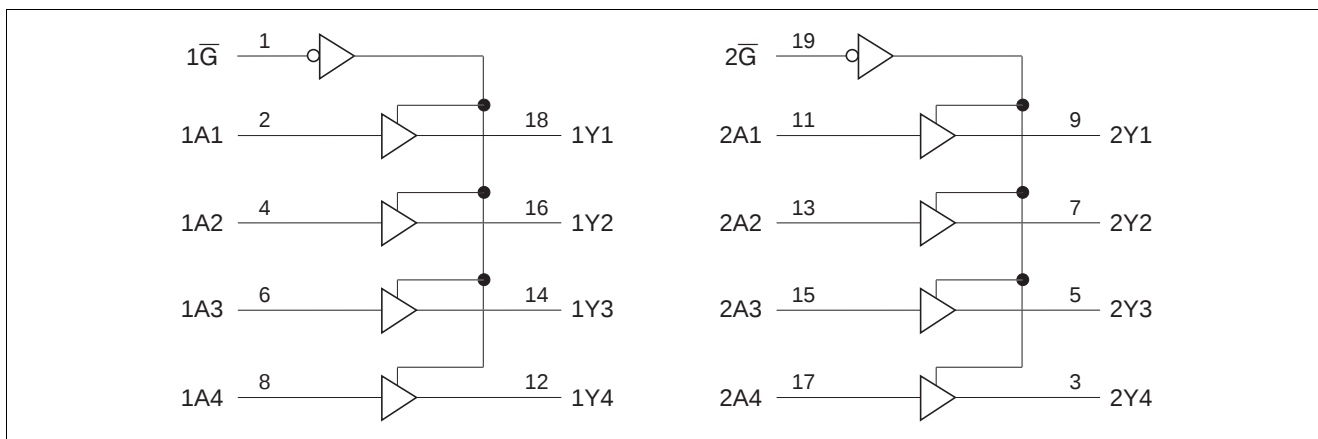
Note: The absolute maximum ratings are values, which must not individually be exceeded, and furthermore, no two of which may be realized at the same time.

Recommended Operating Conditions

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	V_{CC}	2.7 to 5.5	V	At operation
Input voltage	V_I	0 to 5.5	V	
Output voltage	V_O	0 to 5.5 0 to V_{CC}	V	Output "Z" or V_{CC} : OFF Output "H" or "L"
Output current	I_{OH}	-12	mA	$V_{CC} = 2.7$ V
		-24 ^{*1}		$V_{CC} = 3.0$ to 5.5 V
	I_{OL}	12	mA	$V_{CC} = 2.7$ V
		24 ^{*1}		$V_{CC} = 3.0$ to 5.5 V
Input rise / fall time	t_r, t_f	0 to 6	ns / V	
Operating temperature	T_a	-40 to +85	°C	

Note: 1. Duty cycle $\leq$ 50%

Logic Diagram



Electrical Characteristics

(Ta = -40 to 85°C)

Item	Symbol	V _{CC} (V)	Min	Typ	Max	Unit	Test Conditions
Input voltage	V _{IH}	2.7 to 3.6	2.0	—	—	V	
		4.5 to 5.5	V _{CC} ×0.7	—	—		
	V _{IL}	2.7 to 3.6	—	—	0.8	V	
		4.5 to 5.5	—	—	V _{CC} ×0.3		
Output voltage	V _{OH}	2.7 to 5.5	V _{CC} -0.2	—	—	V	I _{OH} = -100 μA
		2.7	2.2	—	—		I _{OH} = -12 mA
		3.0	2.4	—	—		
		3.0	2.2	—	—		I _{OH} = -24 mA
		4.5	3.8	—	—		
	V _{OL}	2.7 to 5.5	—	—	0.2	V	I _{OL} = 100 μA
		2.7	—	—	0.4		I _{OL} = 12 mA
		3.0	—	—	0.55		I _{OL} = 24 mA
		4.5	—	—	0.55		
Input current	I _{IN}	0 to 5.5	—	—	±5	μA	V _{IN} = 0 to 5.5 V
Off state output current	I _{OZ}	2.7 to 5.5	—	—	±5	μA	V _{OUT} = 0 to 5.5 V
	I _{OZPU}	0 to 1.5	—	—	±5		V _{OUT} = 0.5 to 5.5 V,
	I _{OZPD}	1.5 to 0	—	—	±5		Output enable = don't care
Output leak current	I _{OFF}	0	—	—	±5	μA	V _{IN} or V _O = 5.5 V
Quiescent supply current	I _{CC}	2.7 to 3.6	—	—	225	μA	V _{IN} = 3.6 to 5.5 V ^{*1} , I _O = 0
		2.7 to 5.5	—	—	350		V _{IN} = V _{CC} or GND
	ΔI _{CC}	2.7 to 3.6	—	—	500	μA	V _{IN} = one input at (V _{CC} -0.6) V, other inputs at V _{CC} or GND
Input capacitance	C _{IN}	3.3	—	3.4	—	pF	V _{IN} = V _{CC} or GND
Output capacitance	C _O	3.3	—	7.5	—	pF	V _{OUT} = V _{CC} or GND

Note: 1. This applies in the disabled state only.

Switching Characteristics

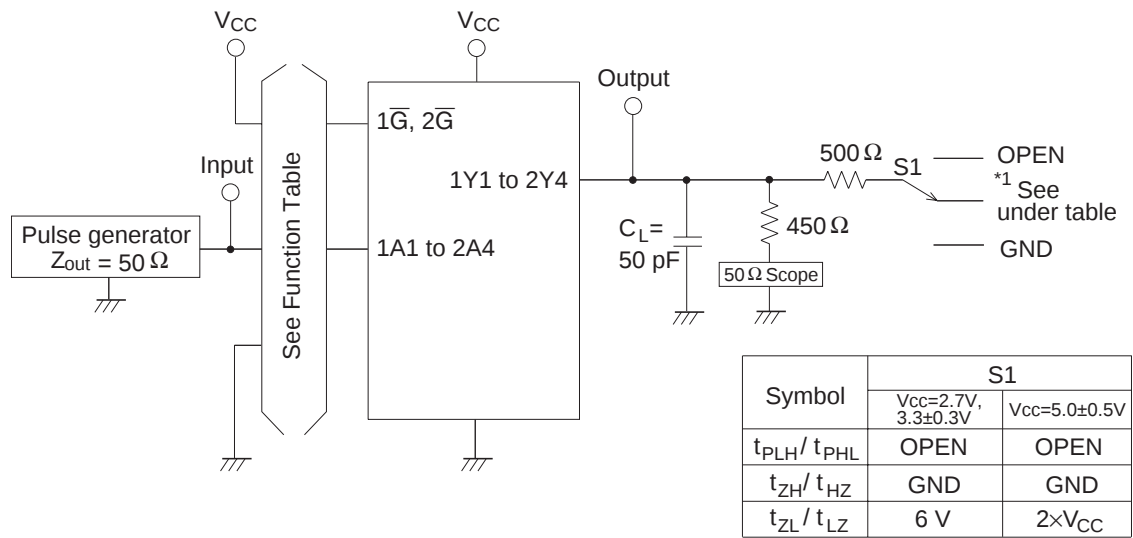
(Ta = -40 to 85°C)

Item	Symbol	V _{CC} (V)	Min	Typ	Max	Unit	FROM (Input)	TO (Output)
Propagation delay time	t _{PLH}	2.7	—	—	6.9	ns	A	Y
	t _{PHL}	3.3±0.3	1.5	—	5.9			
		5.0±0.5	—	—	4.5			
Output enable time	t _{ZH}	2.7	—	—	8.6	ns	$\overline{G}$	Y
	t _{ZL}	3.3±0.3	1.5	—	7.6			
		5.0±0.5	—	—	6.1			
Output disable time	t _{HZ}	2.7	—	—	6.8	ns	$\overline{G}$	Y
	t _{LZ}	3.3±0.3	1.5	—	6.5			
		5.0±0.5	—	—	5.5			
Between output pin skew ^{*1}	t _{OSLH}	2.7	—	—	—	ns		
	t _{OSHL}	3.3±0.3	—	—	1.0			
		5.0±0.5	—	—	1.0			

Note: 1. This parameter is characterized but not tested.

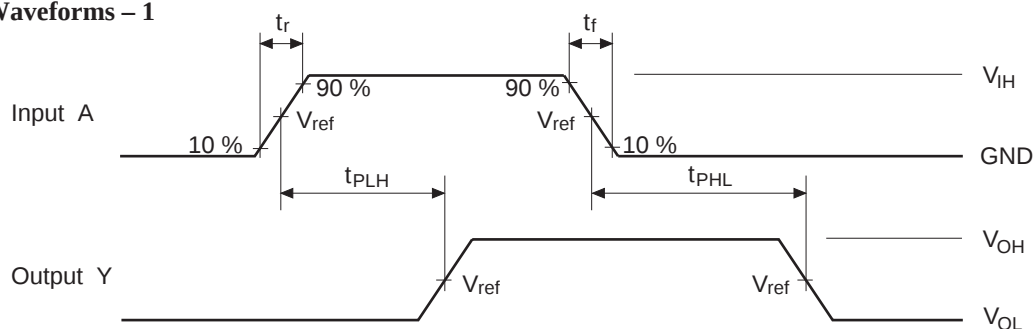
$$t_{OSLH} = |t_{PLHm} - t_{PLHn}|, t_{OSHL} = |t_{PHLm} - t_{PHLn}|$$

Test Circuit

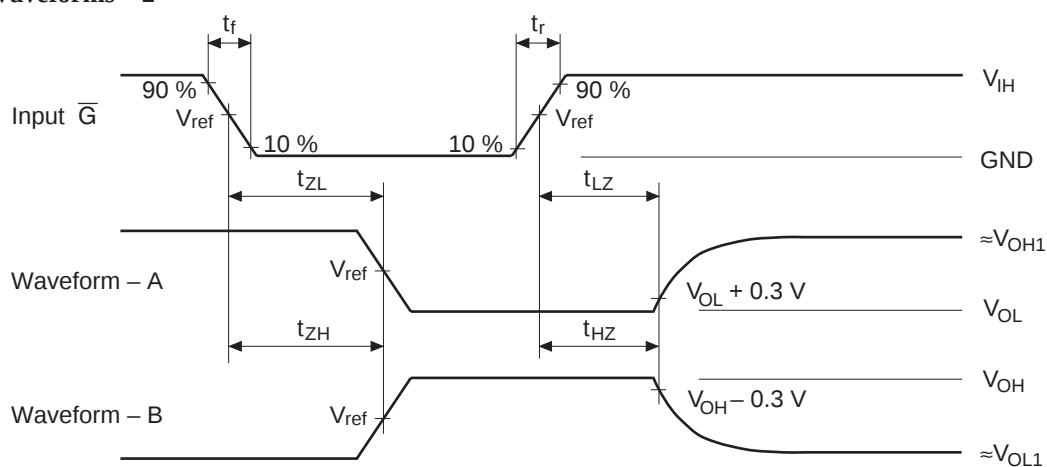


Note: 1. C_L includes probe and jig capacitance.

• Waveforms – 1



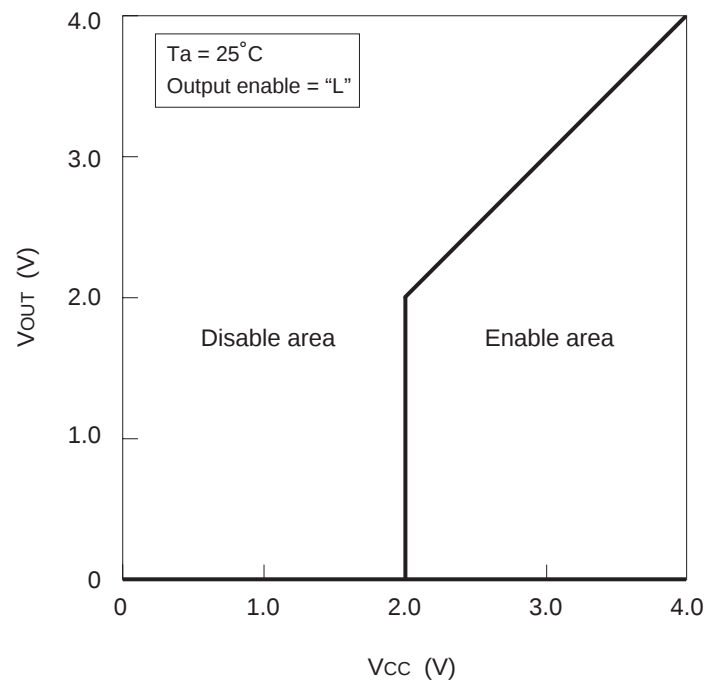
• Waveforms – 2



TEST	$V_{CC}=2.7V, 3.3\pm0.3V$	$V_{CC}=5.0\pm0.5V$
V_{IH}	2.7 V	V_{CC}
V_{ref}	1.5 V	$50\%V_{CC}$
V_{OH1}	3 V	V_{CC}
V_{OL1}	GND	GND

- Notes:
1. Input waveform : PRR = 10 MHz, duty cycle 50%, $t_r = 2.5$ ns, $t_f = 2.5$ ns
 2. Waveform – A shows input conditions such that the output is "L" level when enabled by the output control.
 3. Waveform – B shows input conditions such that the output is "H" level when enabled by the output control.

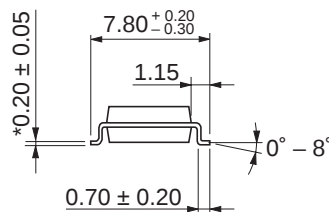
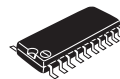
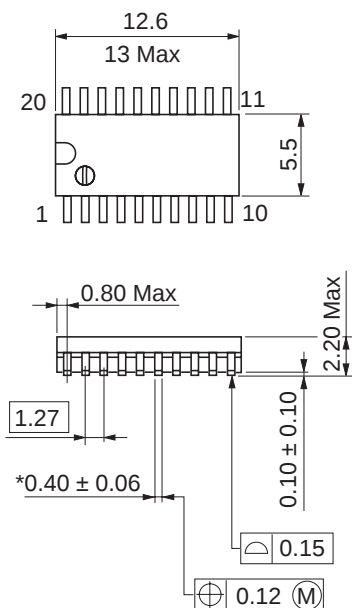
Power up / down Characteristics



Package Dimensions

As of January, 2002

Unit: mm

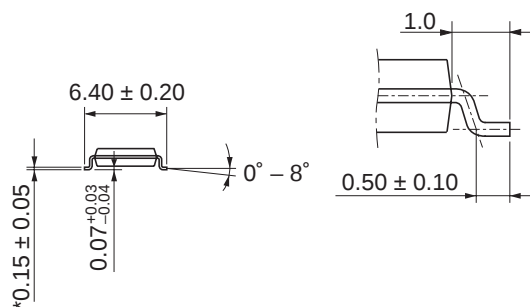
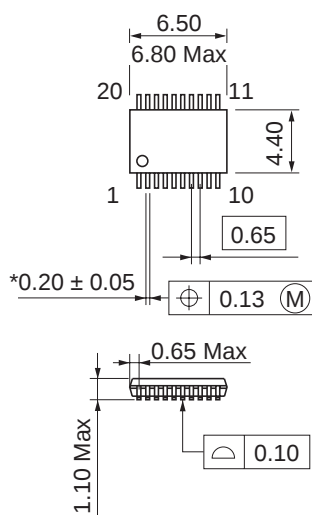


Package Code	FP-20DAV
JEDEC	—
JEITA	Conforms
Mass (reference value)	0.31 g

*Pd plating

As of January, 2002

Unit: mm



Package Code	TTP-20DAV
JEDEC	—
JEITA	—
Mass (reference value)	0.07 g

*Pd plating

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